Preferred Device

# Silicon Pin Diode

This device is designed primarily for VHF band switching applications but is also suitable for use in general–purpose switching circuits. Supplied in a Surface Mount package.

- Rugged PIN Structure Coupled with Wirebond Construction for Optimum Reliability
- Low Capacitance  $0.7 \text{ pF Typ at V}_{R} = 20 \text{ Vdc}$
- Very Low Series Resistance at 100 MHz 0.34 Ohms (Typ)
   @ I<sub>F</sub> = 10 mAdc
- Device Marking: 4D



## ON Semiconductor™

http://onsemi.com

# SILICON PIN SWITCHING DIODE

#### **MAXIMUM RATINGS**

Symbol	Rating	Value	Unit
٧R	Continuous Reverse Voltage	20	Vdc
lF	Peak Forward Current	20	mAdc

#### THERMAL CHARACTERISTICS

Symbol	Characteristic	Max	Unit
PD	Total Device Dissipation FR–5 Board,*  TA = 25°C  Derate above 25°C	200 1.57	mW mW/°C
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	635	°C/W
TJ, T <sub>stg</sub>	Junction and Storage Temperature	150	°C

<sup>\*</sup>FR-4 Minimum Pad



PLASTIC SOD-323 CASE 477



## **ORDERING INFORMATION**

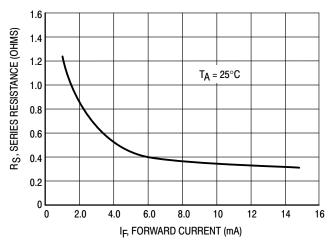
Device	Package	Shipping		
MMVL3401T1	SOD-323	3000 / Tape & Reel		

**Preferred** devices are recommended choices for future use and best overall value.

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I <sub>R</sub> = 10 μAdc)	V(BR)R	35	_	_	Vdc
Diode Capacitance (V <sub>R</sub> = 20 Vdc)	CT	_	_	1.0	pF
Series Resistance (Figure 5) (IF = 10 mAdc, f = 100 MHz)	RS	_	_	0.7	Ω
Reverse Leakage Current (V <sub>R</sub> = 25 Vdc)	IR	_	_	0.1	μAdc

#### **TYPICAL CHARACTERISTICS**



50 40 40 30 T<sub>A</sub> = 25°C 20 0.5 0.6 0.7 0.8 0.9 1.0 V<sub>F</sub> FORWARD VOLTAGE (VOLTS)

Figure 1. Series Resistance

20 10 7.0 5.0 1.0 2.0 1.0 0.7 0.5 0.7 0.5 0.2 +3.0 0 -3.0 -6.0 -9.0 -12 -15 -18 -21 -24 -2 V<sub>R</sub>, REVERSE VOLTAGE (VOLTS)

Figure 2. Forward Voltage

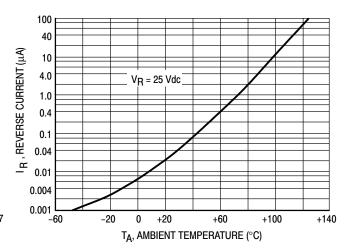
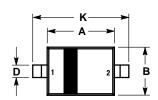


Figure 3. Diode Capacitance

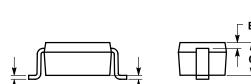
Figure 4. Leakage Current

## **PACKAGE DIMENSIONS**



NOTE 3

SOD-323 PLASTIC PACKAGE CASE 477-02 **ISSUE A** 



- NOTES:

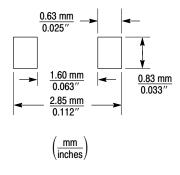
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.60	1.80	0.063	0.071
В	1.15	1.35	0.045	0.053
С	0.80	1.00	0.031	0.039
D	0.25	0.40	0.010	0.016
Е	0.15 REF		0.006 REF	
Н	0.00	0.10	0.000	0.004
J	0.089	0.177	0.0035	0.0070
K	2.30	2.70	0.091	0.106

STYLE 1: PIN 1. CATHODE 2. ANODE



SOD-323 Soldering Footprint

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